



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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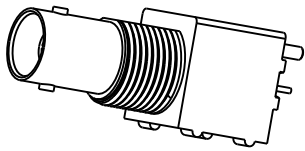
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



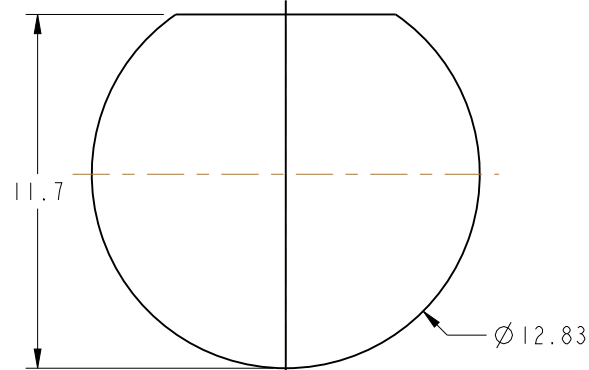
1. MATERIALS AND FINISHES:
 - BODY - ZINC DIE CAST, NICKEL PLATING
 - CONTACT - PHOSPHOR BRONZE, GOLD PLATING (.000003 THICK)
 - @ CONTACT AREA ONLY, TIN PLATING AT TAIL, NICKEL PLATED OVERALL
 - INSULATOR - POLYPROPYLENE
 - HOUSING - PBT 15% G.F., WHITE
 - ROUND PIN - BRASS, TIN PLATING
 - GROUNDNG TERMINAL - STEEL, TIN PLATING
2. ELECTRICAL:
 - A. IMPEDANCE: 50 OHM
 - B. FREQUENCY RANGE: DC - 1 GHz
 - C. DIELECTRIC WITHSTANDING VOLTAGE: 1500 VRMS, MIN.
3. MECHANICAL:
 - A. DURABILITY: 500 CYCLES MIN.
 - B. TEMPERATURE RANGE: -55° C TO 85° C
4. PACKAGING:
 - A. PACKAGED IN PACKING TRAYS
 - B. QUANTITY PER TRAY: 40
5. SEPERATELY SUPPLIED MOUNTING HARDWARE TO BE TIGHTENED
TO 10 IN-LBS MIN/15 IN-LBS MAX
WHEN ASSEMBLING TO PANEL

REVISIONS

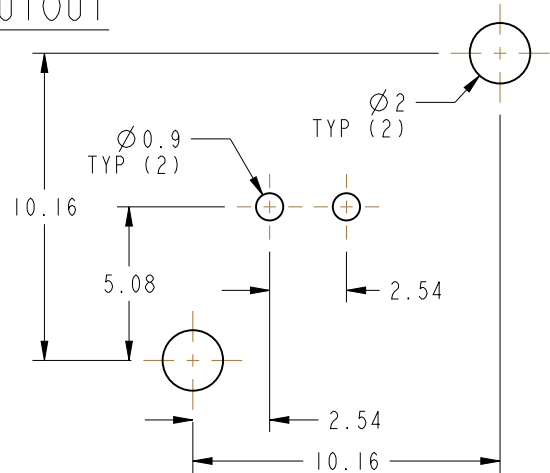
REV	DESCRIPTION	DATE	ECO	APPR
A	RELEASE TO MFG	3/15/90	37099	DR
F	SEE SHEET I	10/11/96	41545	CPM
G	SEE SHEET I	2/3/05	45257	CPM
H	UPDATED FORMAT AND NOMINAL ENVELOPE DIMENSIONS	9/10/12	49195	EW



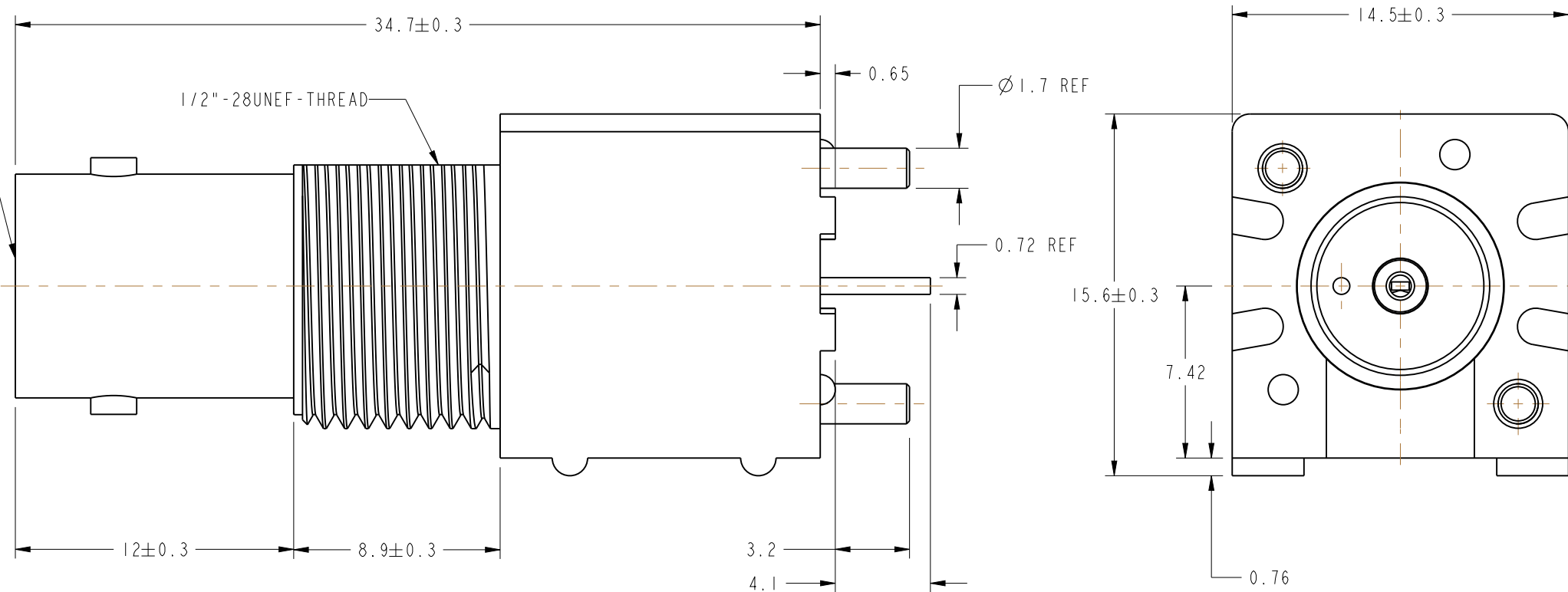
SCALE 1.000



PANEL CUTOUT



RECOMMENDED PCB LAYOUT



ALL OTHER SHEETS ARE FOR INTERNAL USE ONLY

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN METRIC AND TOLERANCES ARE: <0.5mm 0.5 - 6mm 6 - 30mm 30 - 120mm ANGLES ± 0.05mm ±0.1mm ±0.2mm ± 0.3mm ±1° NOTICE - These drawings, specifications, or other data (1) are, and remain the property of Amphenol corp. (2) must be returned upon request; and (3) are confidential and not to be disclosed to any person other than those to whom they are given by Amphenol Corp. the furnishing of these drawings, specifications, or other data by Amphenol Corp., or to any other person to anyone for any purpose is not to be regarded by implication or otherwise in any manner licensing, granting rights to permitting such holder or any other person to manufacture, use or sell any product, process or design, patented or otherwise, that may in any way be related to or disclosed by said drawings, specifications, or other data.	MATERIAL -	DRAWN ERIC WANKOFF	DATE 31-Jul-12	TITLE 50 OHM BNC STR JACK, ISOLATED		Amphenol RF www.amphenolrf.com	
		ENGINEER D. ROYCE	DATE 15-Mar-90				
	REFERENCE	APPROVED D ROYCE	DATE 15-Mar-90	SCALE: 4.0:1.0	SHEET 2 OF 2	DRAWING NO. 31-5493	
	CONFIGURATION LEVEL:	CAD FILE	DWG SIZE B		REV H	ITEM NO. 31-5493	
	FINISH					PART NO. 31-5493	